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PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Wataru NAGATOMO	03/30/2012
Yuichi ABE	03/30/2012
Mitsuji IKEDA	03/30/2012

RECEIVING PARTY DATA

Name:	HITACHI HIGH-TECHNOLOGIES CORPORATION	
Street Address:	24-14, Nishi-Shimbashi 1-chome	
City:	Minato-ku, Tokyo	
State/Country:	JAPAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13502823

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: 108004.64476US

NAME OF SUBMITTER: Michael H. Jacobs

Total Attachments: 1

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PATENT REEL: 028314 FRAME: 0850

Attorney Docket Number: 108004.64476US

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI HIGH-TECHNOLOGIES CORPORATION. a corporation organized under the laws of Japan, located at 24-14, Nishi-Shimbashi 1-chome, Minato-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI HIGH-TECHNOLOGIES CORPORATION, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

PATTERN MATCHING METHOD AND PATTERN MATCHING APPARATUS

* PCT International Application Number PCT/JP2010/005976 filed on October 6, 2010

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI HIGH-TECHNOLOGIES CORPORATION, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI HIGH-TECHNOLOGIES CORPORATION.

Signed on the date(s) indicated aside signatures:

	INVENTOR(S)	Date Signed
	(発明者フルネームサイン)	(署名日)
1) _	Wataru Nagatomo	3/30/2012
2)	Wataru Nagatomo Wataru NAGATOMO Yuichi Ale	3/30/2012
3)	Yuichi ABE Mitsuji Ikeda Mitsuji IKEDA	3/30/2012
, <u>-</u>	Mitsuji IKEDA	
4) _		
5)		
6) _		
7) _	,	
8) _		
9)		

PATENT REEL: 028314 FRAME: 0851

RECORDED: 06/05/2012